

Americas Summit

Our Wireless Advantage

**Wireless is The Foundation in
Innovation, Development and
Commercialization**

**RAJESH PANKAJ,
Senior Vice President, Engineering**



The Fundamental Reason to Buy Smart Devices?



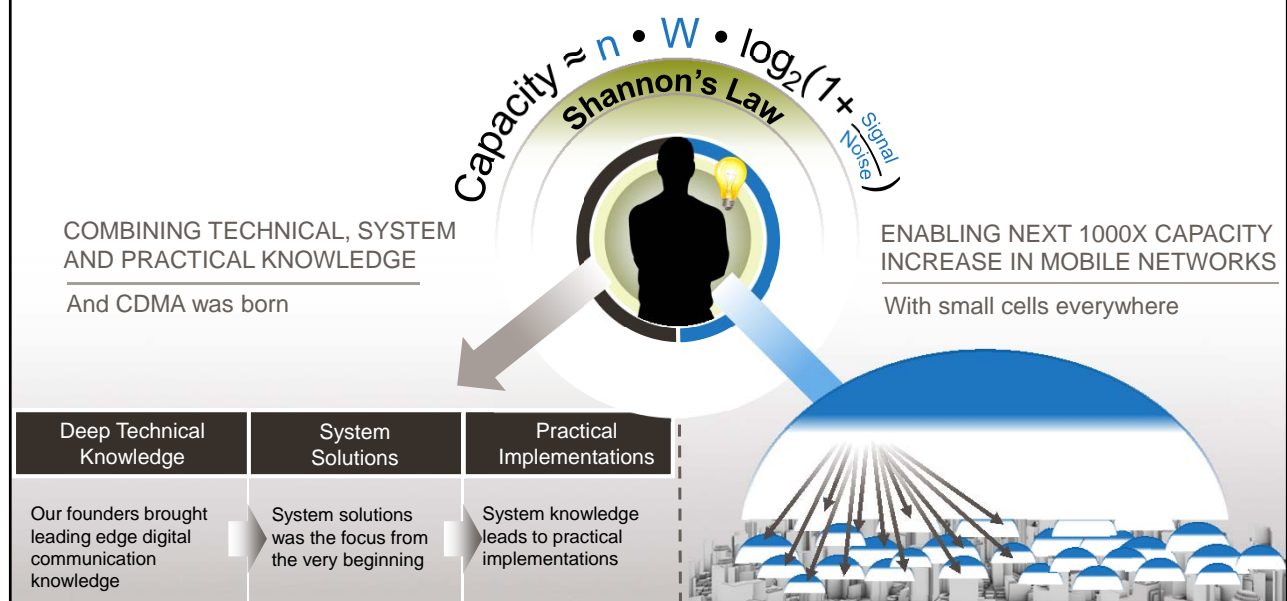
The Qualcomm Difference



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WIRELESS IS THE FOUNDATION IN OUR INNOVATION,
DEVELOPMENT AND COMMERCIALIZATION

Wireless is Our Heritage—27 Years Of Leadership



Optimizing Power and Performance in Wireless



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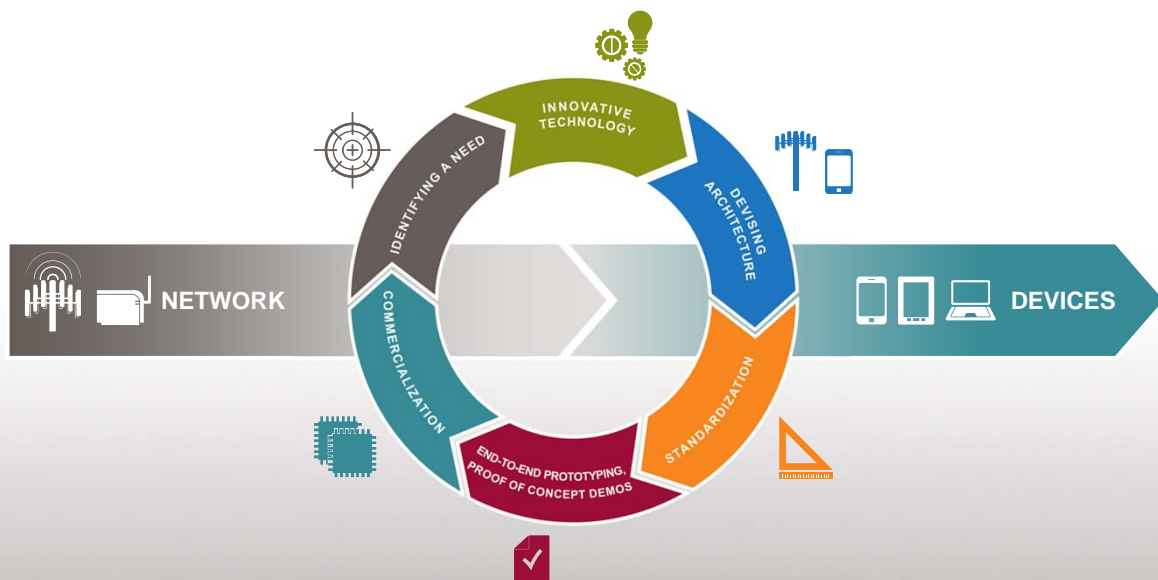
The Qualcomm Difference



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 SYSTEM VIEW CRUCIAL
IN OVERALL DESIGN

End-to-End, System Wide Innovation Approach

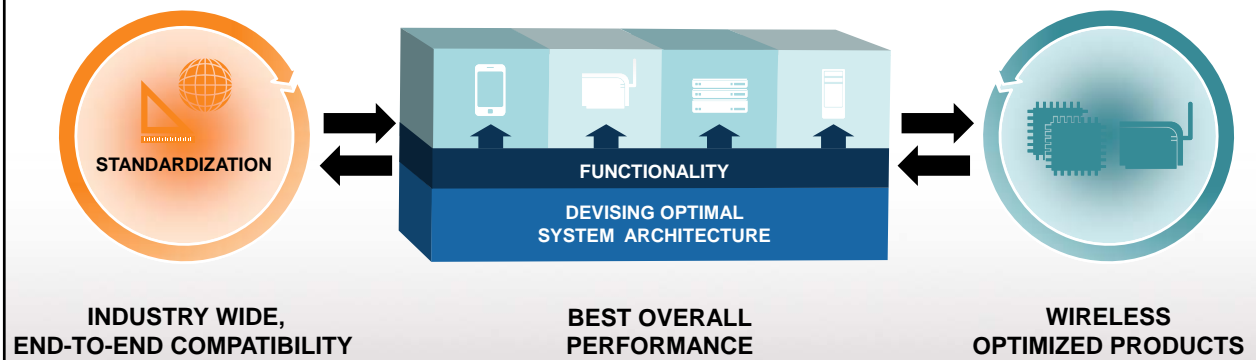


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Example: Pioneering LTE Advanced HetNets



Devising System Architecture



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Standards Leadership

Driving Industry Adoption

Standards are the vehicle for industry adoption

Driving Interoperability

Complex wireless system requires standards



Breadth and Depth

Active in standards across the whole stack: Radio, IP mobility, Multimedia, Codecs, ...

Industry Wide Innovation

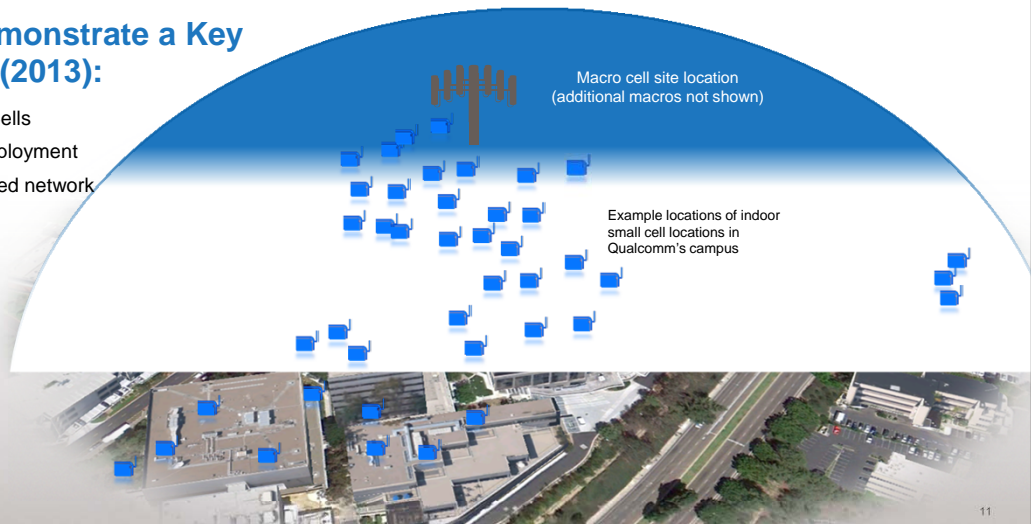
Innovation adopted by standards brings benefits the whole industry

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End-to-End Prototyping—Proof of Concept Demos

We Plan To Demonstrate a Key 1000x Enabler (2013):

- ▶ Neighborhood Small Cells
- ▶ Unplanned, ad-hoc deployment
- ▶ Controlled and managed network
- ▶ Indoor and outdoor
- ▶ Seamless mobility



Source: Google Earth

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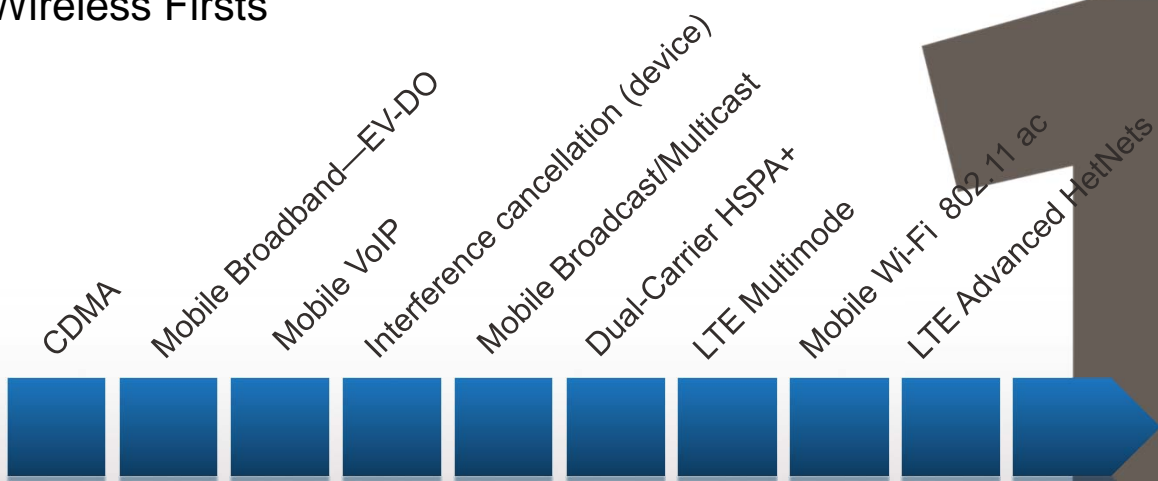
The Qualcomm Difference



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OPTIMIZED PERFORMANCE BASED
ON LEADING EDGE TECHNOLOGIES

Wireless Firsts



Our Hands-on Experience Drives Practical Solutions


Example: Increasing capacity with no impact on standards nor network



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Success of Driving Dual-Carrier HSPA+

102 DC-HSPA+ out of 254 Commercial HSPA+ Networks



STANDARDS LEADERSHIP

- Major 3GPP contributor
- Recognized expertise

INDUSTRY-FIRST DEMOS

- MWC 2008: dual-carrier
- MWC 2009: dual-carrier 42 Mbps

INDUSTRY-FIRST CHIPSETS

Chipset	Launched
MDM 8200 HSPA+	February 2009
MDM 8220 DC-HSPA+	August 2010

We are committed to continue evolving HSPA+

Source: www.gsacom.com, Nov 2012

First with Mobile 802.11ac



► Many product firsts

- Pioneered 5GHz Wi-Fi chip
- 3-stream Wi-Fi 11n chip and first access point on a chip
- "channel bonding" to double Wi-Fi throughput
- Hybrid network combining wired and wireless technologies

► Continued product and innovation leadership

- Enhancing Multi user MIMO
- Tri-band¹ WiGig (802.11 ad) for in-room multi-gigabit wireless docking, displays, audio, and more
- 802.11 ah for sensor, control, extremely long battery life

¹First to deliver a tri-band (dual-band 11n plus WiGig 60 GHz) solution in the form of a module for computers

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**BALANCING POWER AND PERFORMANCE
IN A MOBILE ENVIRONMENT**

The Modem is The Foundation—The Bar is Getting Higher

Then you can integrate mobile processing and multimedia components

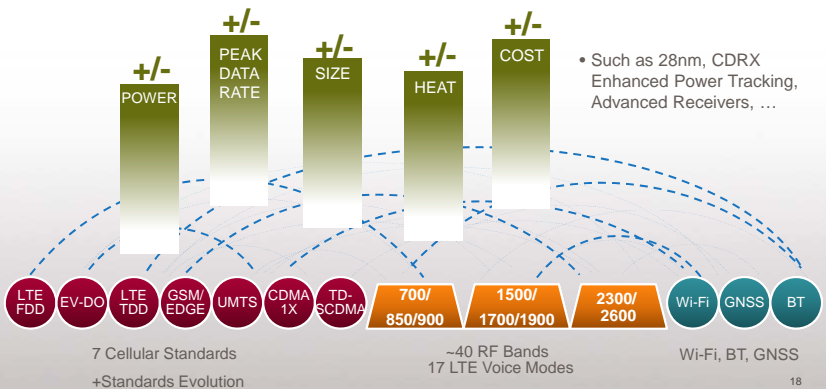


THE BAR IS GETTING HIGHER AND HIGHER

Optimize power and performance in a mobile environment

Solve interworking complexity

Support all technologies, bands, modes, ...



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Summary



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WIRELESS IS THE FOUNDATION IN OUR INNOVATION,
DEVELOPMENT AND COMMERCIALIZATION

Thank You

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